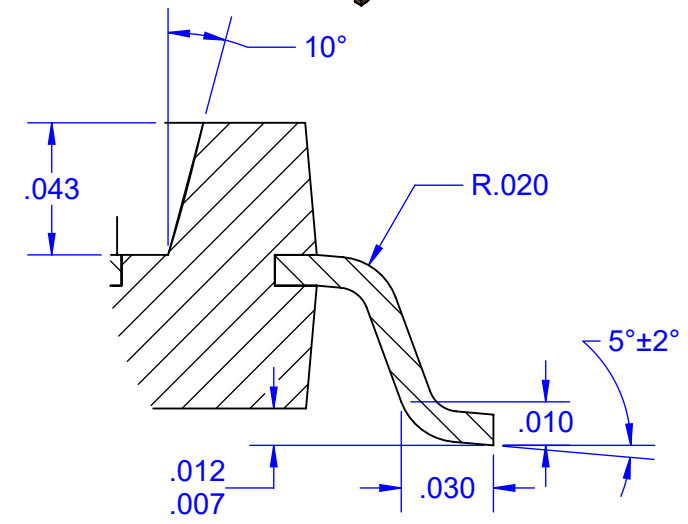
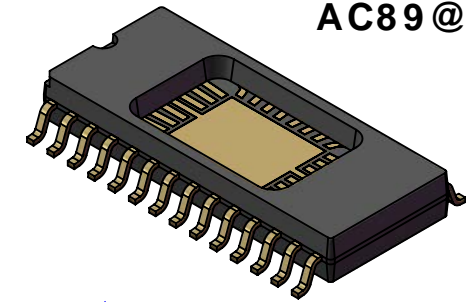
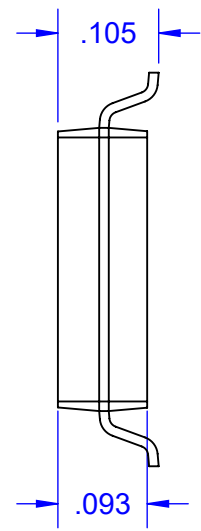
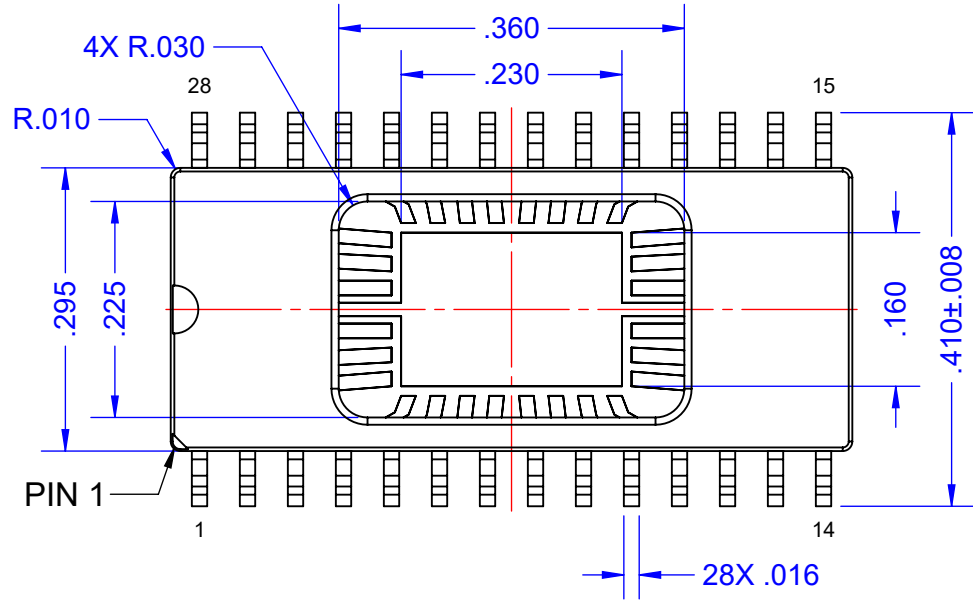


HCDJ9K

9B8J9K

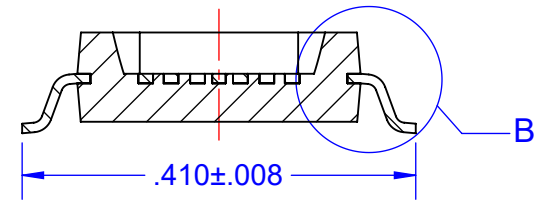
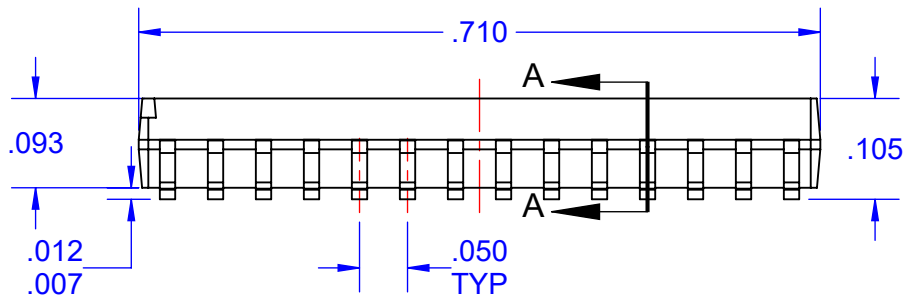
AC89@



DETAIL B
SCALE 16 : 1


G89J9K

SECTION A-A

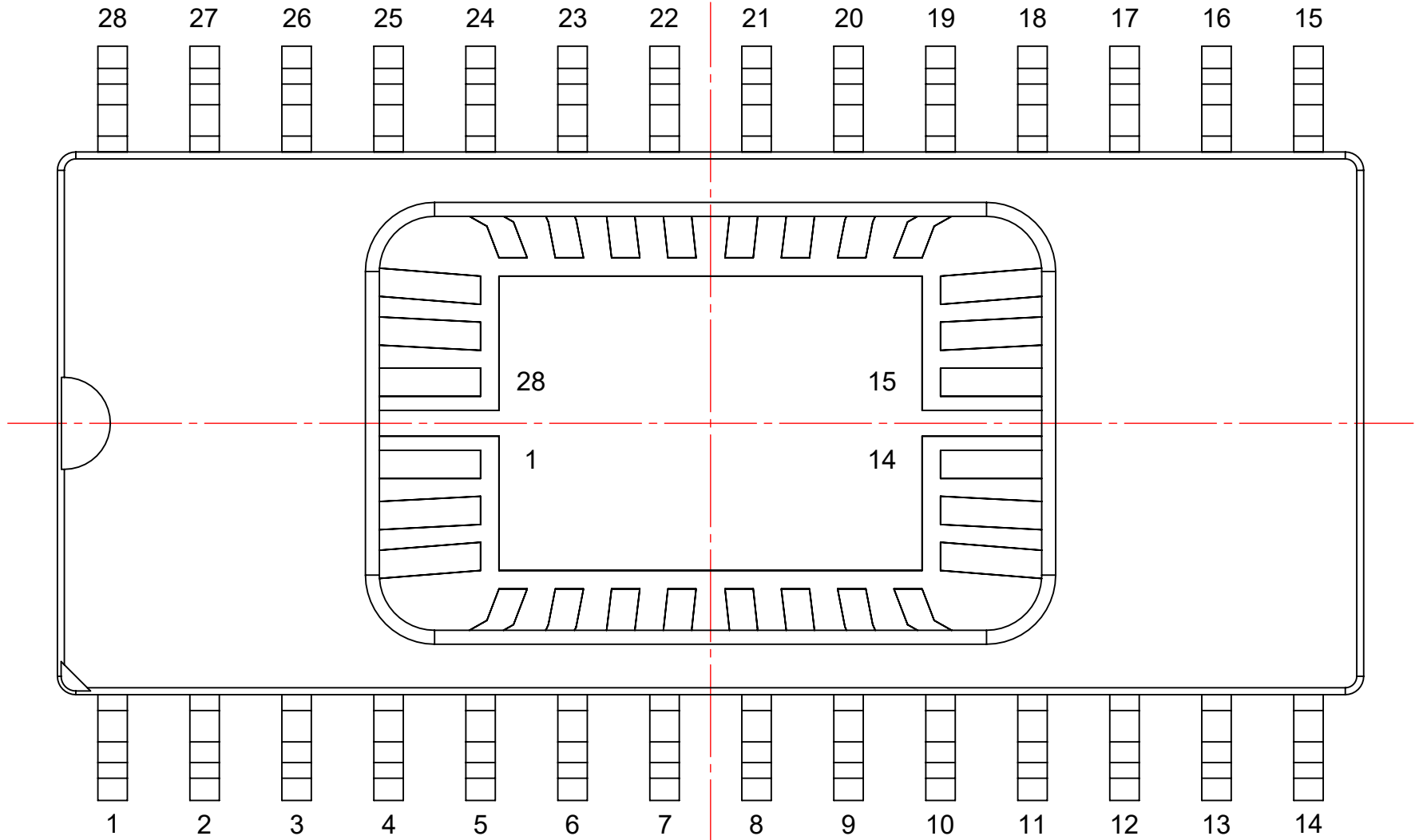


Notes: (Unless Otherwise Specified).

- 1) DIMENSIONS: INCHES [MM].
- 2) PACKAGE CONFORMS TO JEDEC MS-013.
- 3) BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.
- 4) LEAD FRAME: COPPER ALLOY A194 FULL HARD.
- 5) PLATING: NICKEL 100~300 MICRONS (2.5~7.6µm) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.

APPROVALS		DATE	 TITLE SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE			
DRAWN	T.Au	5/1/2021				
ENG	M. Hart	5/1/2021	SCALE	SIZE	DRAWING NO.	REV
MFG			5:1	A	120228	A
QA			DO NOT SCALE DRAWING		SHEET 1 OF 4	
CUST						
REVISED						

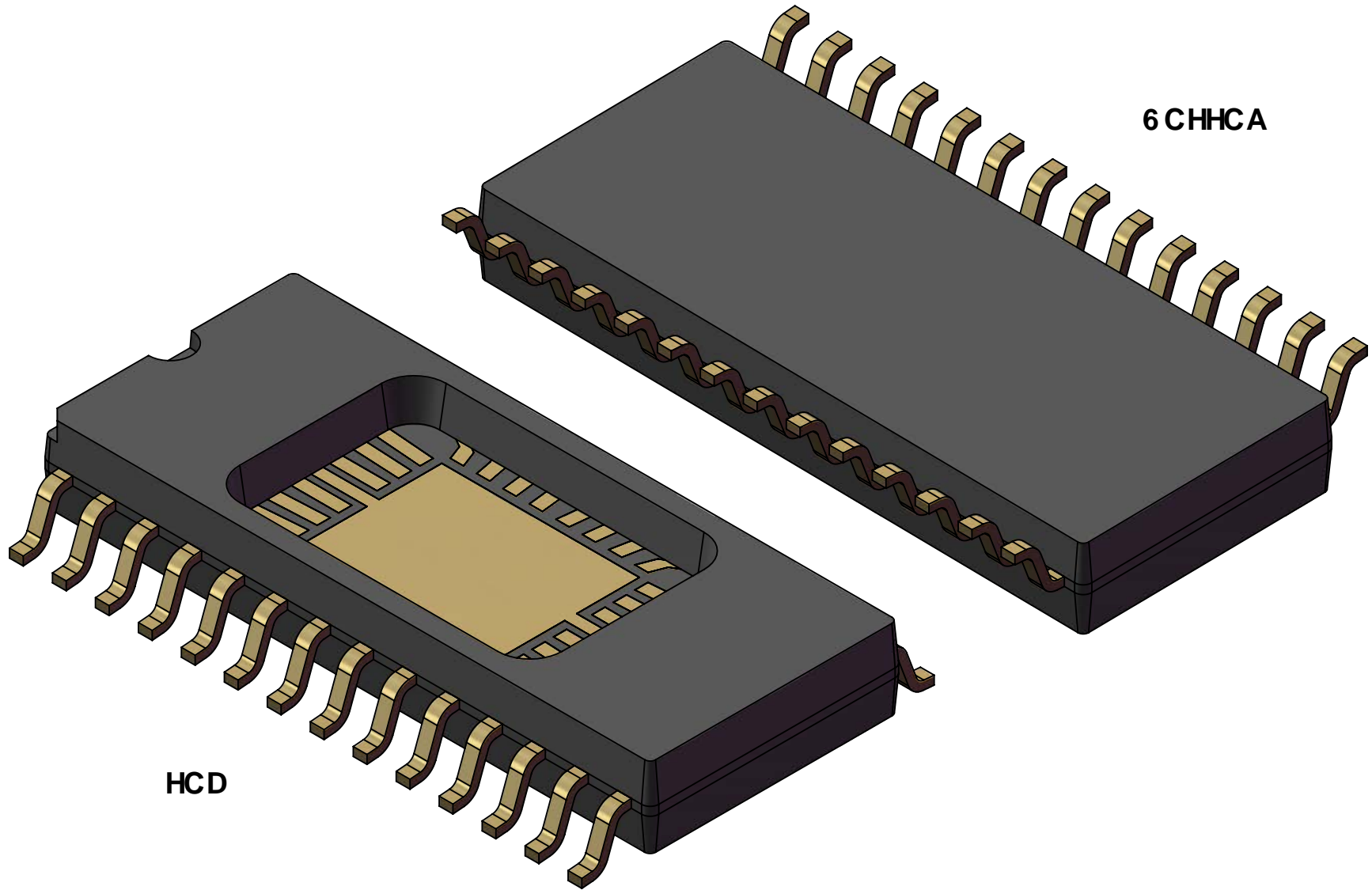
6CB8'8-5; F5A



TITLE			
SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
10:1	A	120228	A
DO NOT SCALE DRAWING			SHEET 2 OF 4

AC89@

6 CHHCA



HCD



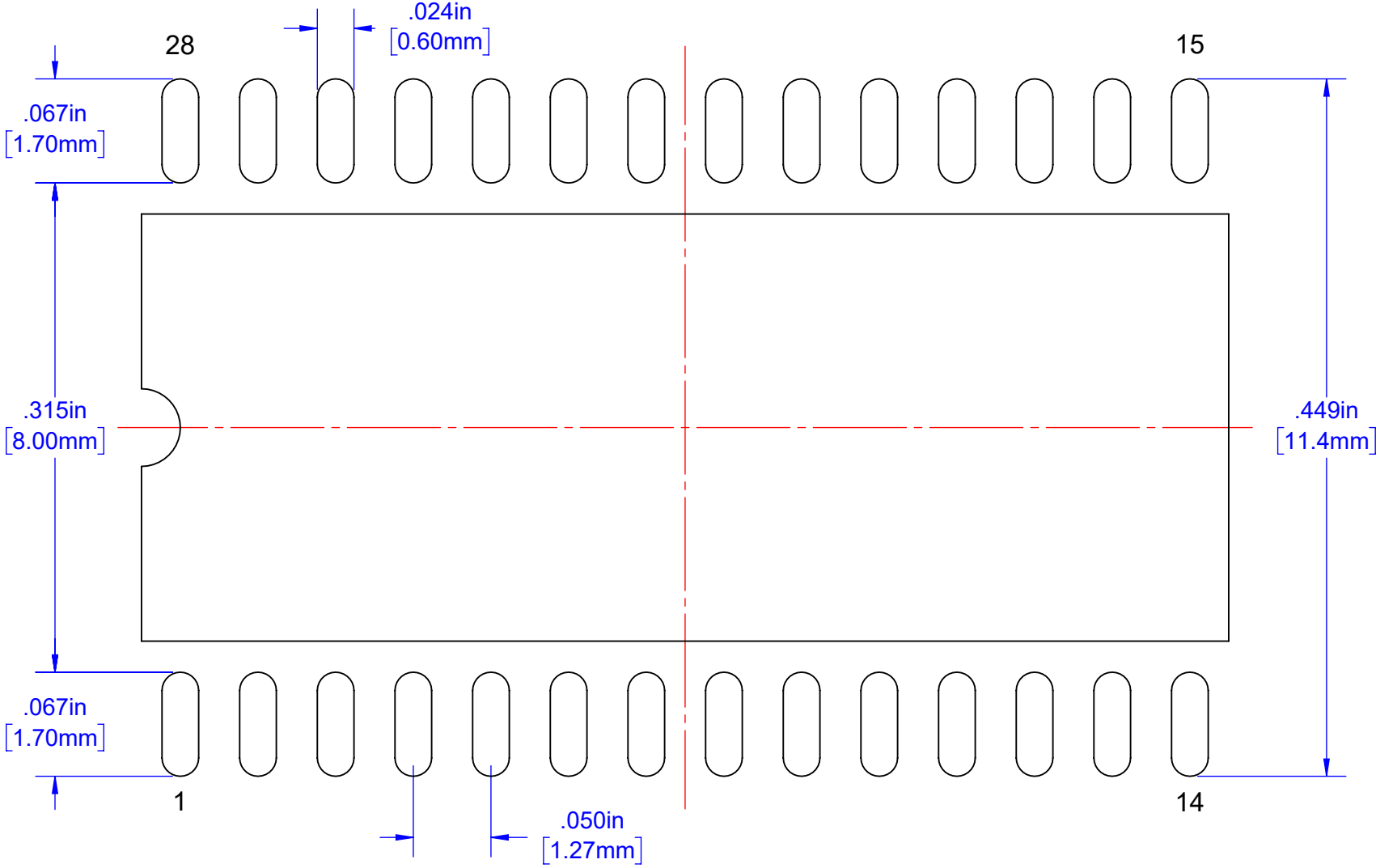
TITLE SOL 28LD PITCH 1.27MM
OPEN CAVITY PACKAGE

SCALE 8:1	SIZE A	DRAWING NO. 120228	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 4

GI ; ; 9GH98 `D7 6
@ B8 `D5 HH9 FB



TITLE SOL 28LD PITCH 1.27MM OPEN CAVITY PACKAGE			
SCALE 10:1	SIZE A	DRAWING NO. 120228	REV A
DO NOT SCALE DRAWING		SHEET 4 OF 4	